

FIG. 1A

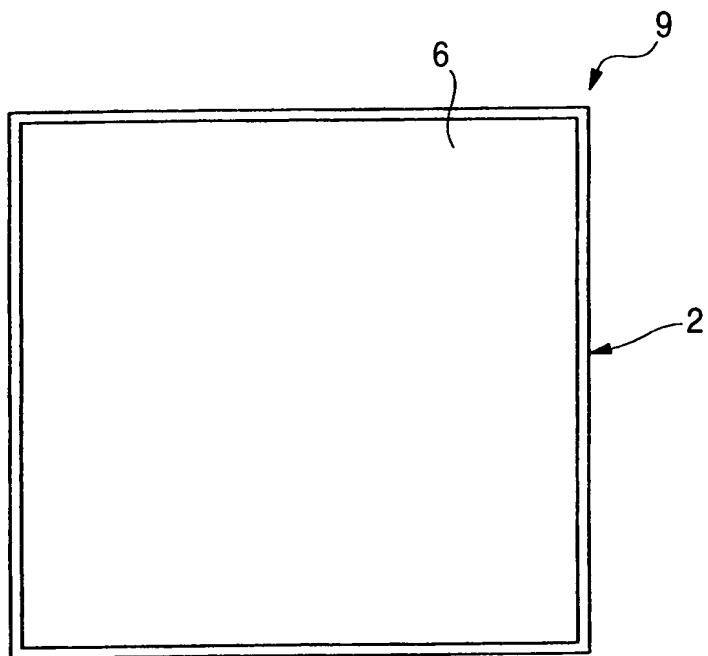
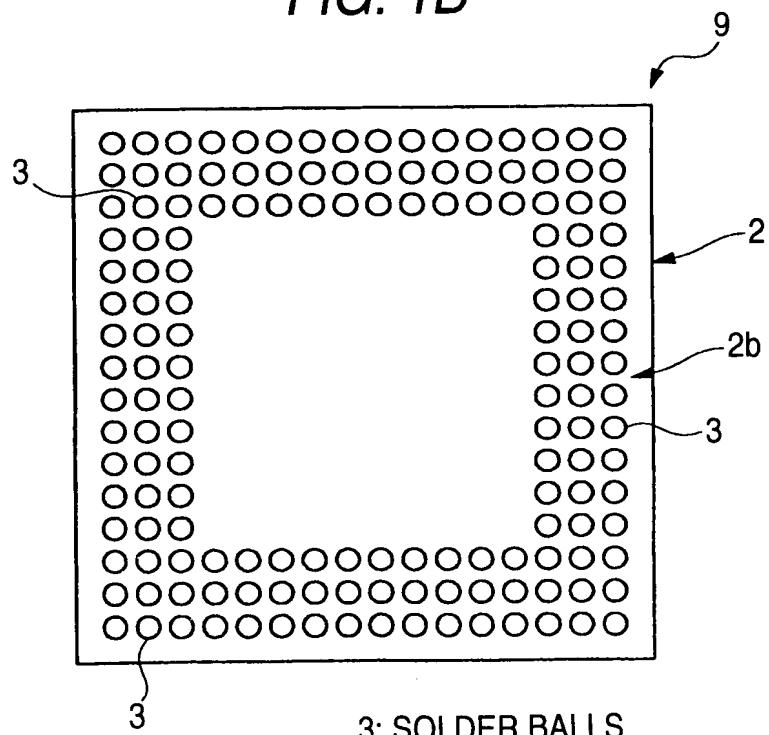
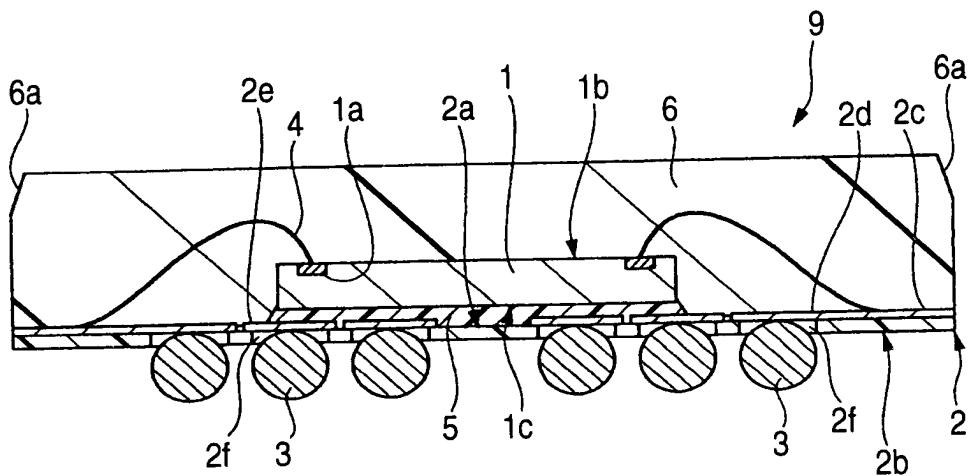


FIG. 1B



3: SOLDER BALLS
6: SEALED PORTION
9: CSP (SEMICONDUCTOR DEVICE)

FIG. 2



1a: PADS (SURFACE ELECTRODES)

2c: CONNECTION TERMINALS (ELECTRODES)

FIG. 3A

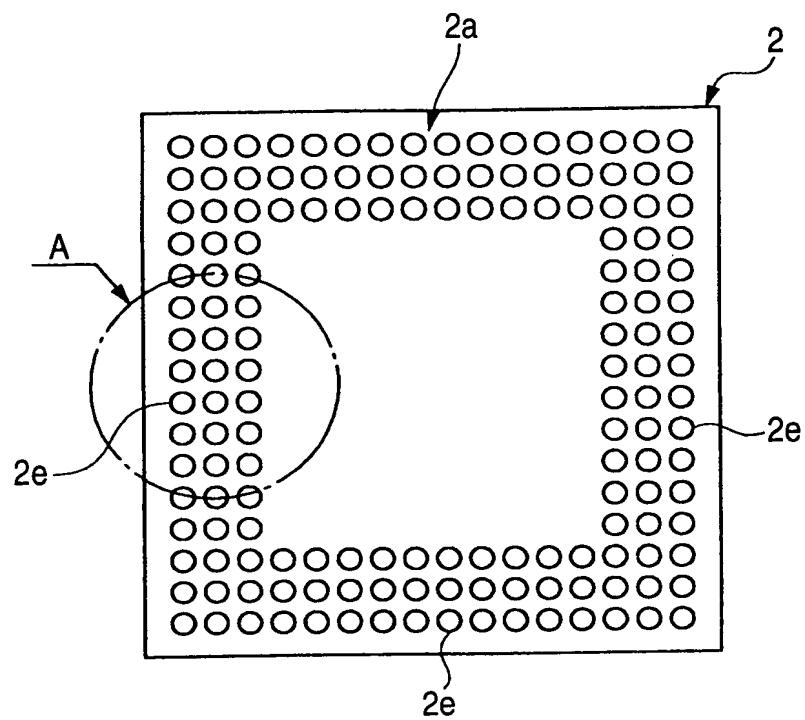


FIG. 3B

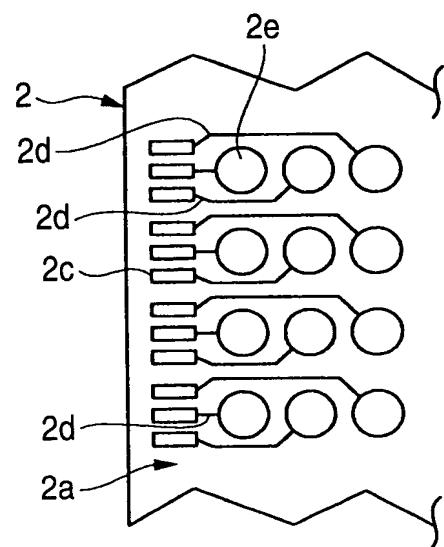
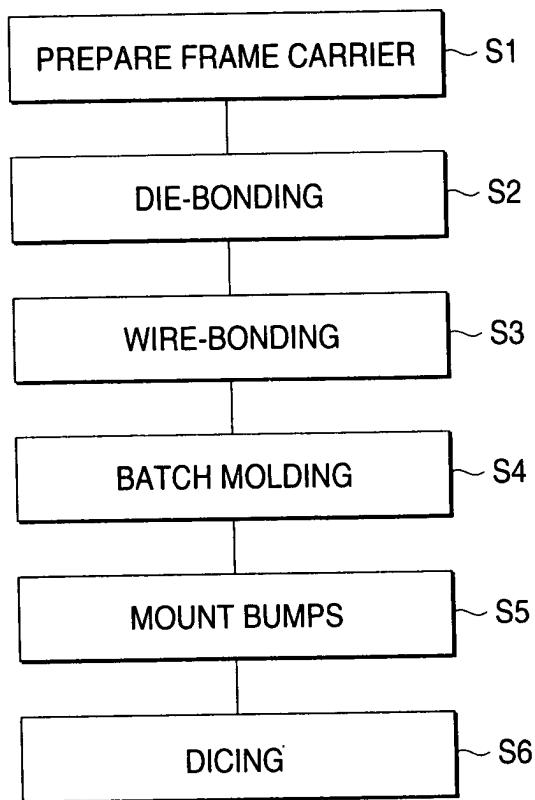


FIG. 4

01000000000000000000000000000000



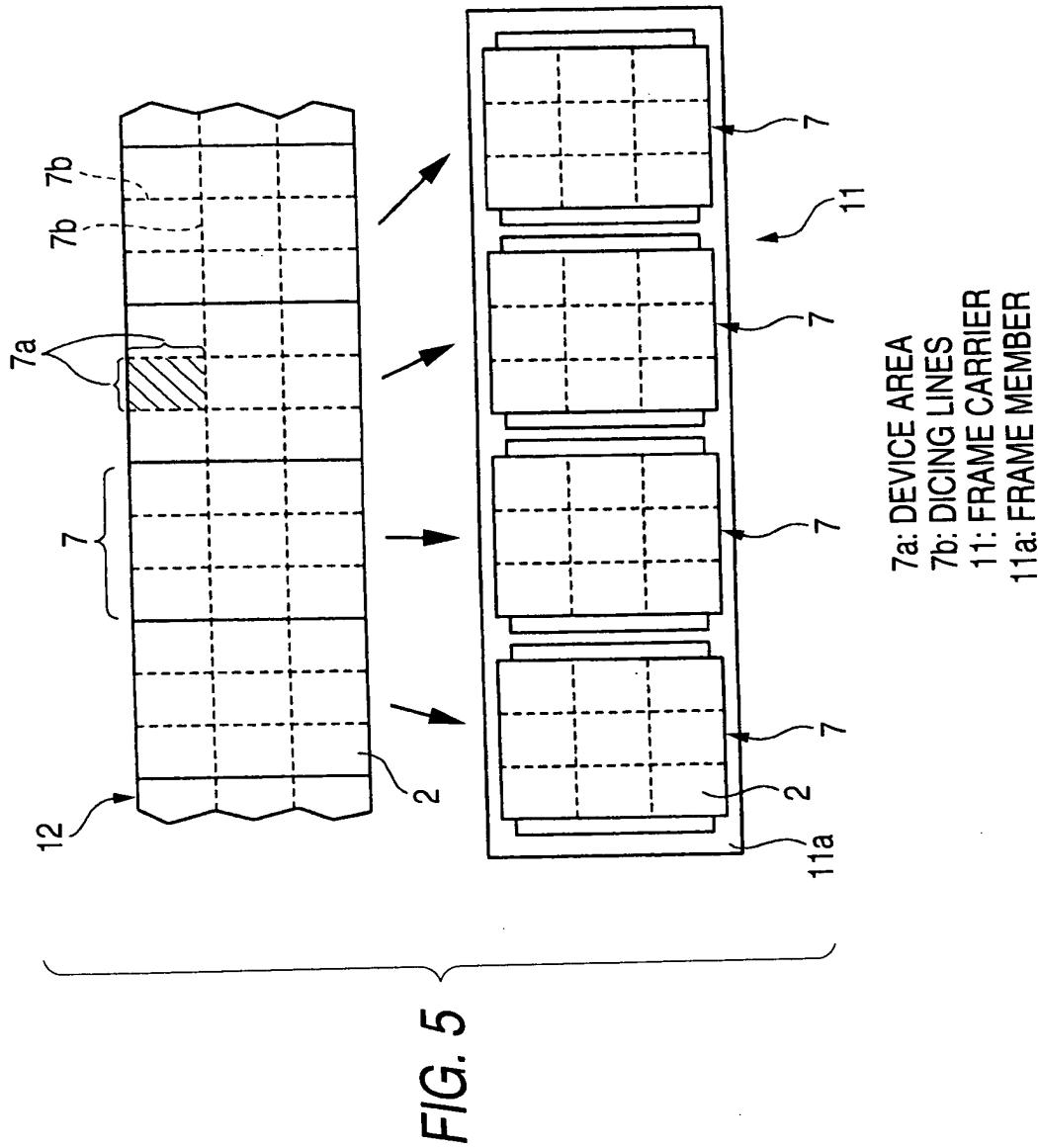
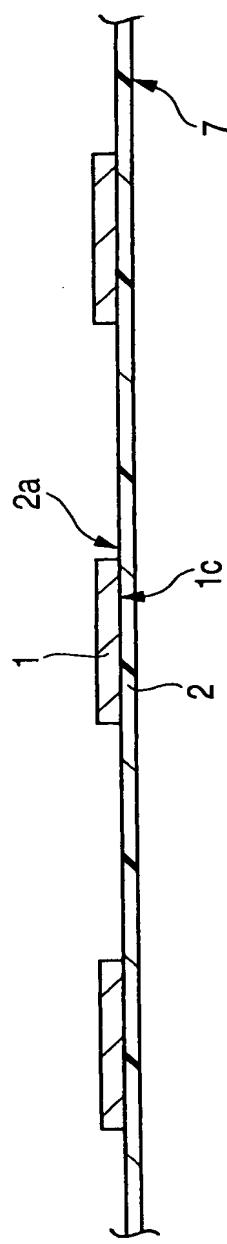
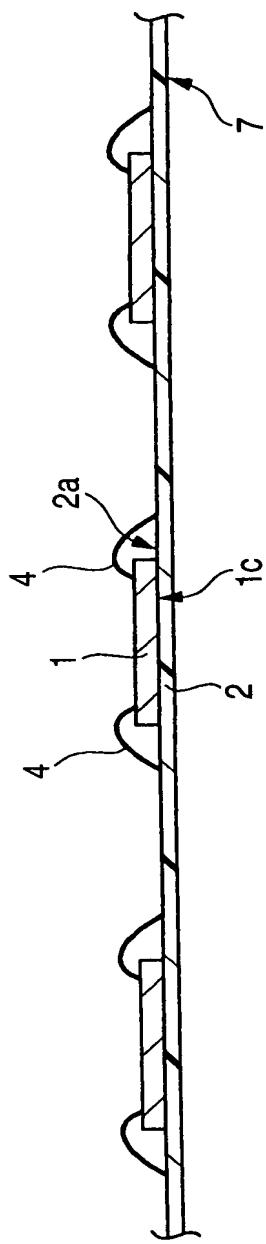


FIG. 6



7/17

FIG. 7



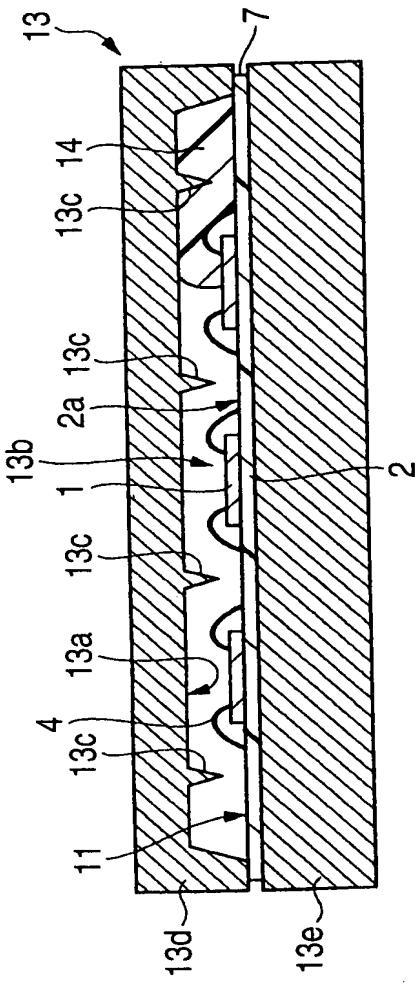
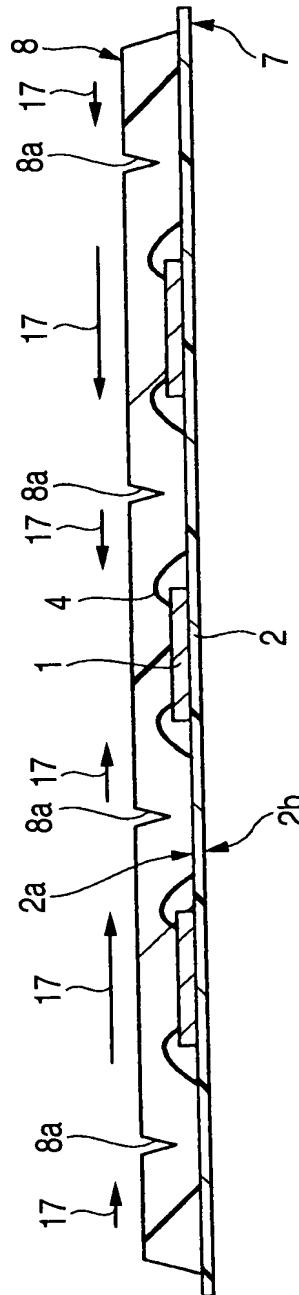
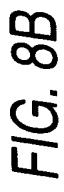
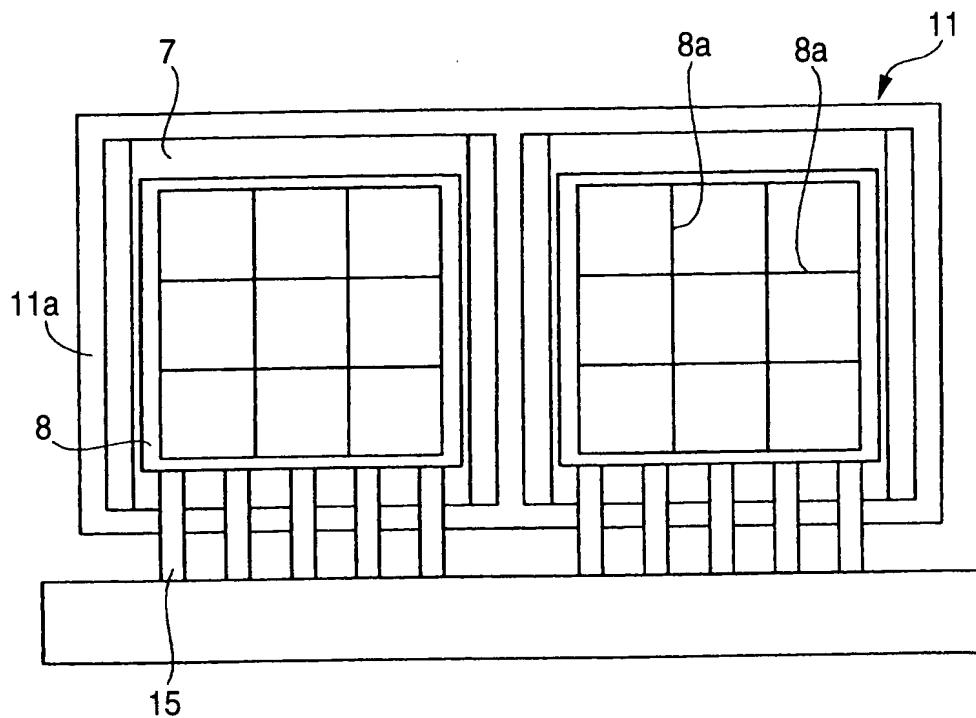


FIG. 8A



| | |
|--|---|
| 1: SEMICONDUCTOR CHIP | 8: BLOCK-MOLDED PORTION (BATCH-SEALED PORTION) |
| 2: TAPE SUBSTRATE (CHIP SUPPORTING SUBSTRATE) | 8a: GROOVES |
| 2a: CHIP SUPPORTING FACE | 13: MOLDING TOOL |
| 2b: BACK FACE (OPPOSITE FACE) | 13a: CAVITY FORMING FACE |
| 4: WIRES (CONDUCTIVE MEMBERS) | 13b: CAVITY |
| 7: MULTI-DEVICE SUBSTRATE | 13c: PROTRUSIONS |
| | 14: MOLDING RESIN |

FIG. 9



10/17

FIG. 10

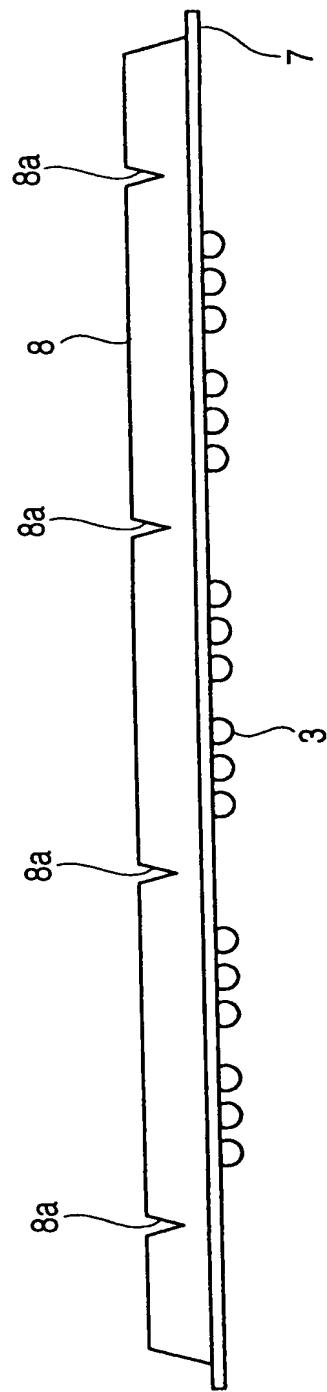


FIG. 11A

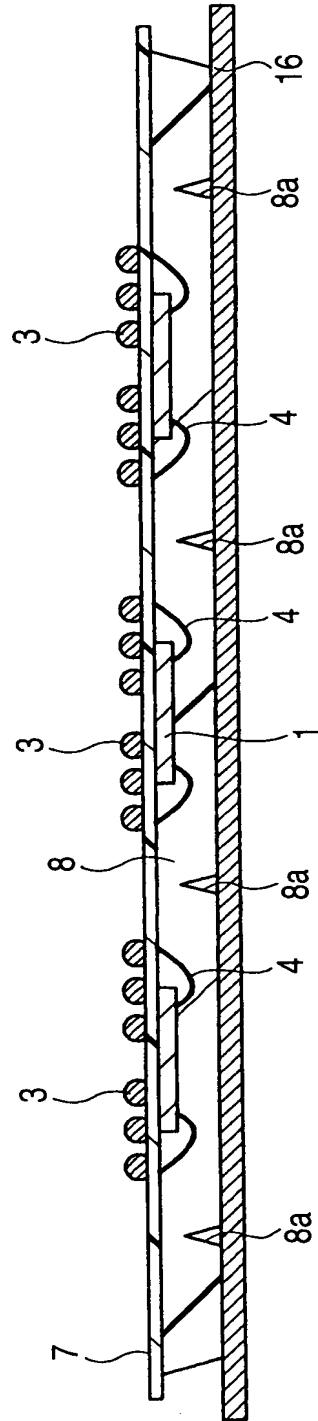
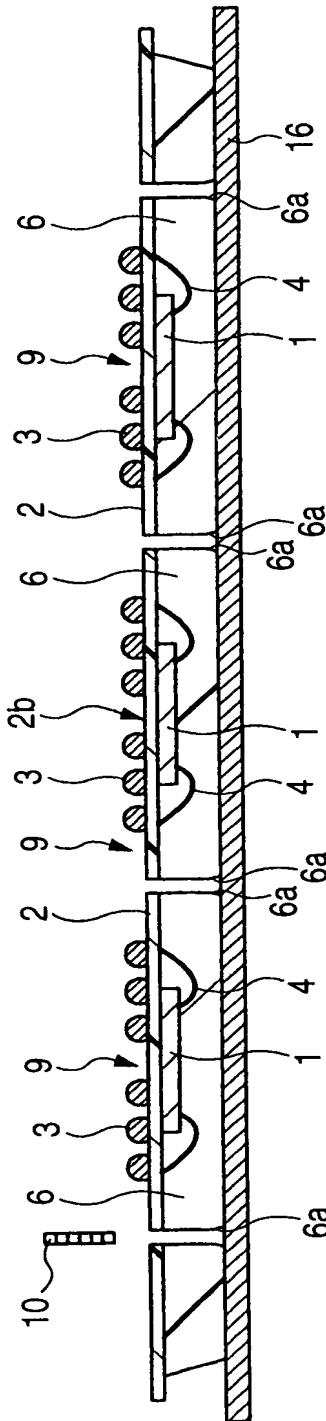


FIG. 11B



10: BLADE

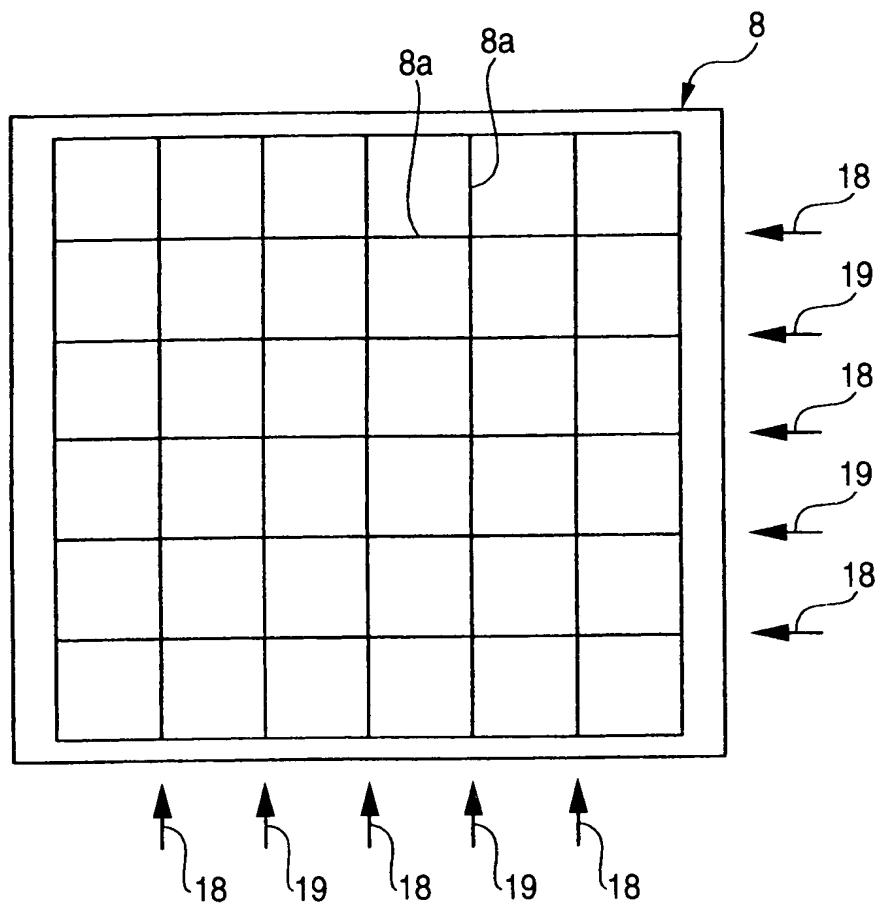
FIG. 12

FIG. 13

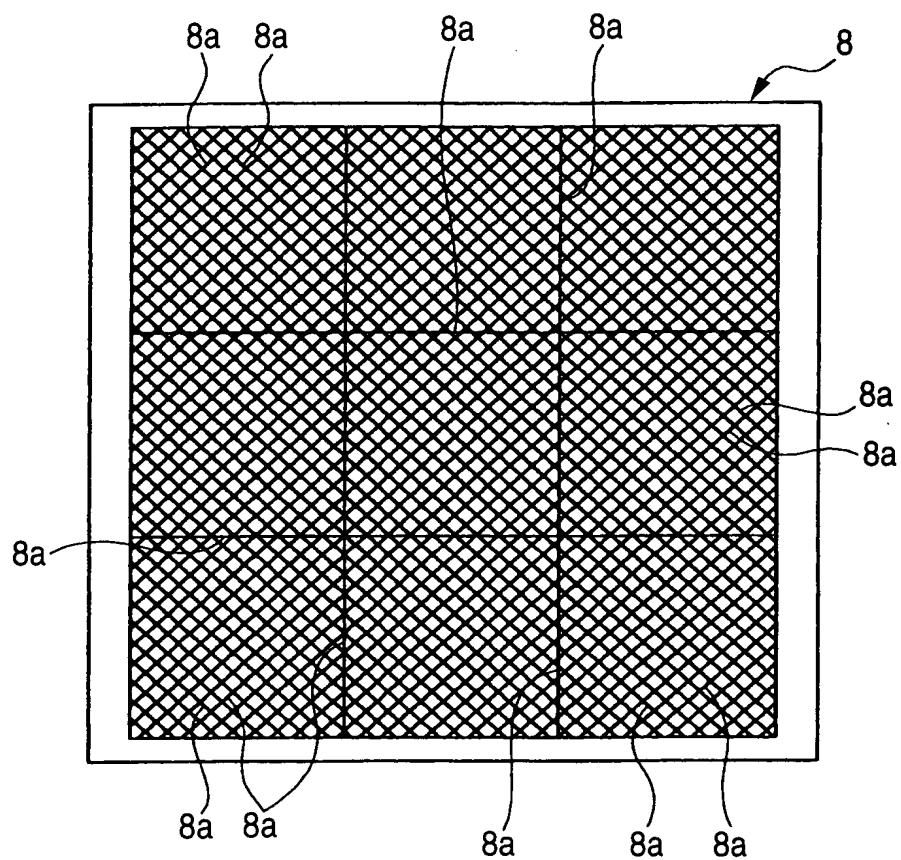


FIG. 14

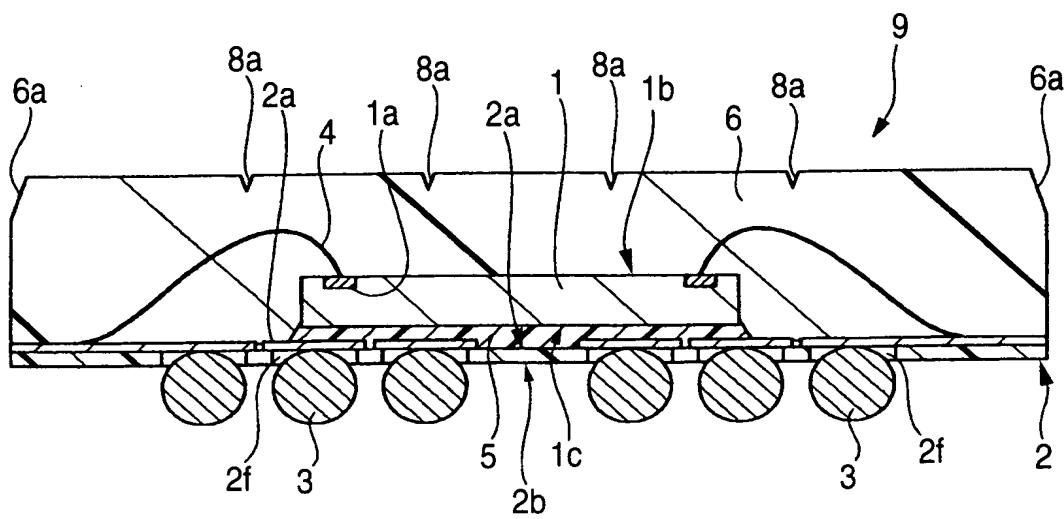


FIG. 15

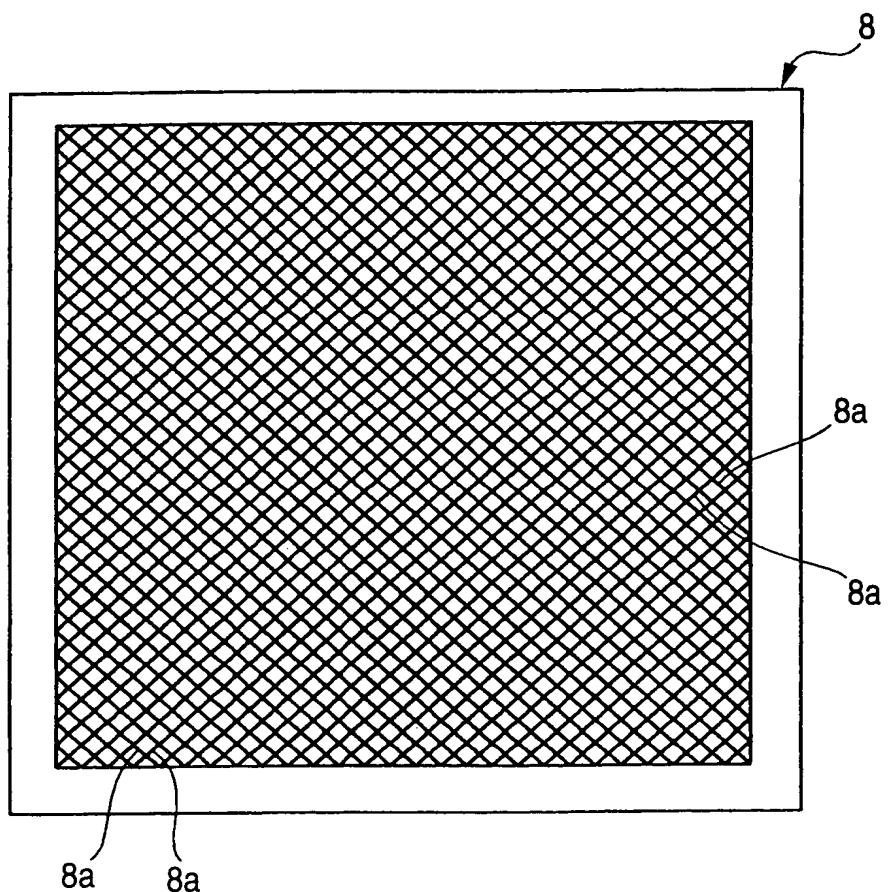


FIG. 16

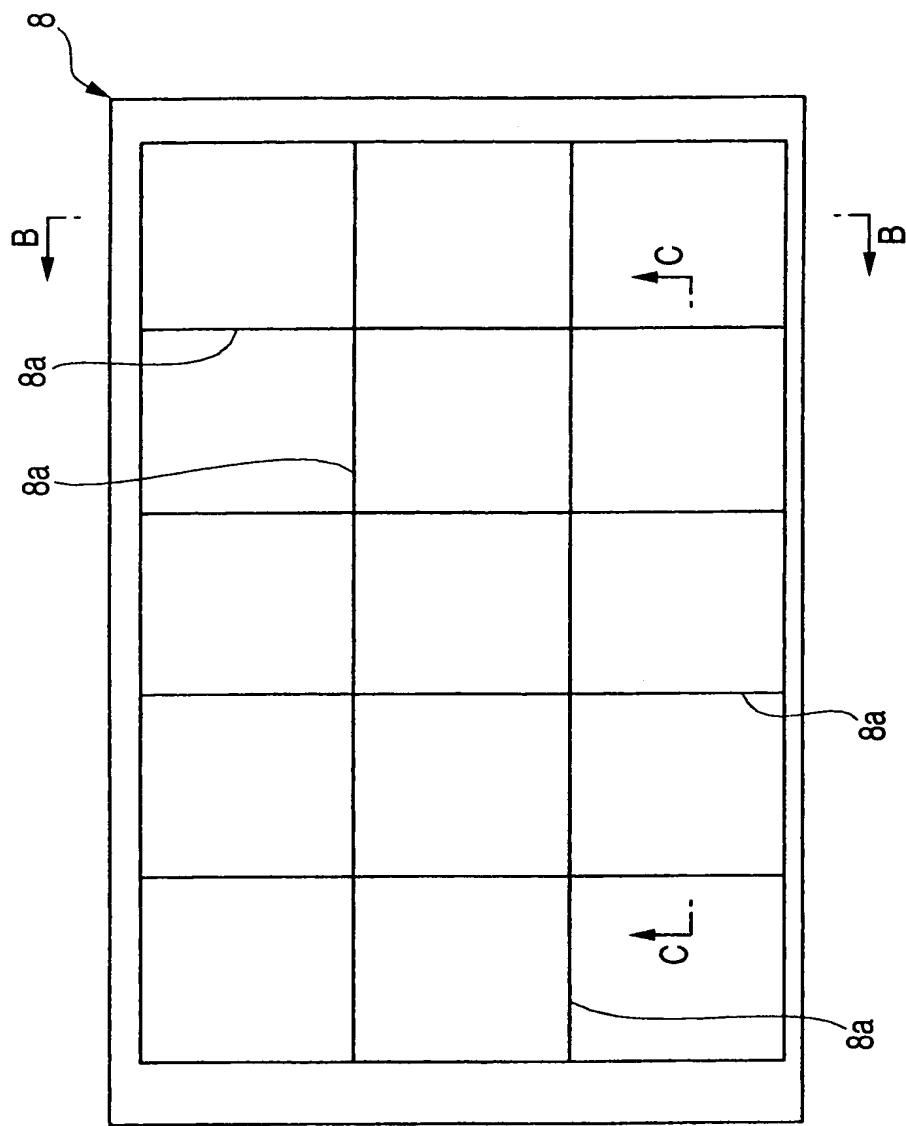


FIG. 17A

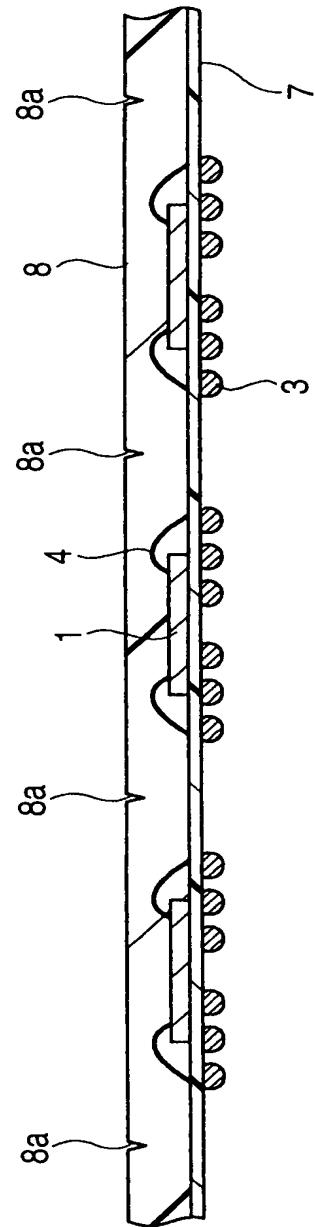


FIG. 17B

